

124-33-F

ELECTRICALLY CONDUCTIVE, TRANSFERABLE, THERMOPLASTIC ADHESIVE FILM

DESCRIPTION:

124-33-F is an electrically conductive, transferable, thermoplastic adhesive film. Some applications for the 125-33-F series include, but are not limited to, conductive splicing of ribbon cables, PTF circuits, and electrical attachment of SMD devices, as well as the assembly of electrical and electronic components. This system features excellent thermal stability and high temperature properties. This product has been formulated to have improved handleability. This product is available in thicknesses from 1 to 5 mils (see product codes below). Other thicknesses are available upon request.

GENERAL FILM DESCRIPTION

Substrate Type: PET Release Liner
 Conductive Coating Type: Silver/Polymer

Product Code	Adhesive Thickness (mils)
124-33-F1	1
124-33-F2	2
124-33-F3	3
124-33-F4	4
124-33-F5	5

TYPICAL CURED PROPERTIES

Property	Value	Units
Useful Temperature Range	-55 to 200	°C
Volume Resistivity	0.0005	Ω - cm
Solderable	No	
Glass Transition Temperature	100	°C
Lap Shear Strength, min.	250	Psi

SHELF LIFE

12 months at room temperature.

PROCEDURE FOR APPLYING:

- As with all adhesive bonds, surface preparation is a vital part of the process. Carefully clean both surfaces to be bonded with MEK if possible. If MEK is not compatible with the surfaces to be bonded, another suitable solvent may be used.
- Allow cleaned surfaces to dry completely.
- Die cut 124-33-F to the of the size of interface area, remove one of the protective liners, position onto one of the surfaces to be bonded, and warm the substrate/adhesive to 125°C or more.
- By applying pressure, laminate the film/adhesive to the substrate smoothing out any trapped air. Allow to cool to room temperature and peel off the other release liner.
- Position the other substrate and apply a clamp to provide constant pressure.
- Cure for 10 minutes at 170°C.
- Remove pressure. Part is ready for use.

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